## PATENT APPLICATION

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2-20-02

C. Hammar

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

M. Kistner et al.

Examiner:

Appl. No.:

09/967,269

Art Unit:

Filing Date: September 28, 2002

Docket:

97-064B

February 20, 2002

For:

Combined Superplastic Forming and Adhesive Bonding

**Assistant Commissioner for Patents** 

Washington, DC 20231

## RECEIVED TO 1700

## INFORMATION APPLICANT CITES THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

Sir:

Applicant files this Information Disclosure Statement prior to the first action. No fee is due. In the event that Applicant should owe a fee, however, please charge that fee to Deposit Account 02-2960. Should Applicant owe a fee (including any fees under §1.17 or all required extension of time fees), please charge that fee to Deposit Account 02-2960. Please treat this paper (and any future reply) as incorporating a petition for extension of time for the appropriate length of time, in the event that an extension is required.